IMPROVED APPARATUS AND METHOD FOR PLANARIZATION OF SPIN-ON MATERIALS

ABSTRACT

An improved and new apparatus and process for planarization of spin-on materials has been developed. The key features of the apparatus and the process are an enclosure surrounding the spin-on table and substrate and the application of a planarization pressure plate to the substrate, subsequent to dispersal of the spin-on materials and during rotation of the substrate.

FIGURE 1 IS SUGGESTED FOR PUBLICATION